

September 2009

BAS16SL Small Signal Diodes

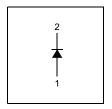
Features

- Low Forward Voltage Drop
- Fast switching
- · Very Small and Thin SMD package
- Profile height, 0.43mm max
- Footprint, 1.0 x 0.6 mm



SOD-923 Marking: AB

Connection Diagram



Absolute Maximum Ratings * $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Value	Unit
V_{RRM}	Maximum Repetitive Reverse Voltage	85	V
I _{F(AV)}	Average Rectified Forward Current	150	mA
I _{FSM}	Forward Surge Current (8.3mS Single Half Sine-Wave)	500	mA
T _{J,} T _{STG}	Operating Junction & Storage Temperature Range	-55 to +150	°C

^{*} These ratings are limiting values above which the serviceability of the diode may be impaired. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

Symbol	Parameter	Value	Unit
P _D	Power Dissipation	227	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient *	520	°C/W

^{*} Minimum land pad.

$\textbf{Electrical Characteristics} \quad \textbf{T}_{A} \text{=-} 25^{\circ} \text{C unless otherwise noted}$

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V_{R}	Breakdown Voltage	I _R = 100μA	85		V
V _F	Forward Voltage	$I_F = 1mA$ $I_F = 10mA$ $I_F = 50mA$ $I_F = 150mA$		715 855 1.0 1.25	mV mV V
I _R	Reverse Leakage	V _R = 75V V _R = 25V@150°C V _R = 75V@150°C		1.0 30 50	μΑ μΑ μΑ
trr	Reverse Recovery Time	$I_F = I_R = 10 \text{mA}, \text{ irr} = 0.1 I_R$		8.0	nS
C _j	Junction Capacitance	$V_R = 0, f = 1.0MHz$		2.0	pF

Typical Performance Characteristics

Figure 1. Forward Current Characteristics

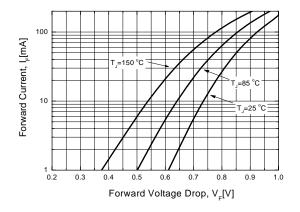


Figure 2. Reverse Leakage Current

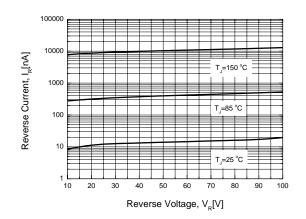


Figure 3. Junction Capacitance

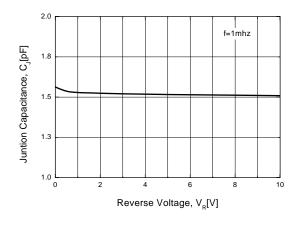
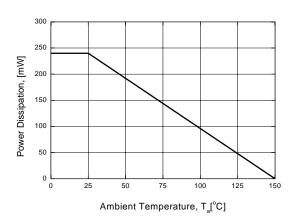
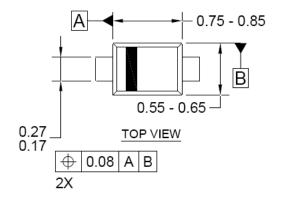
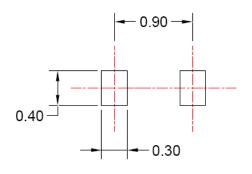


Figure 4. Power Derating

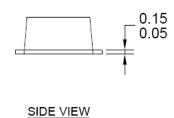


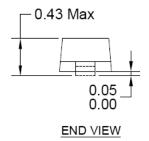
Package Dimension





LAND PATTERN RECOMMENDATION





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- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- E) DRAWING FILE NAME: SOD923F02REV1





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Definition of Terms				
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